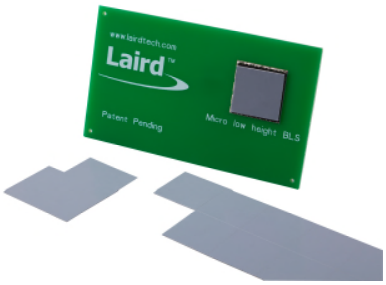
Tflex UT20000 Series

Ultra-Thin Thermal Gap Filler



Product Description

Tflex™ UT20000 is a specially formulated ultra-thin gap filler thermal interface material designed for thin interfaces that offers excellent thermal performance and high compliancy. It is designed without embedded reinforcing fiberglass to minimize contact resistance, yet still allows easy material handling and durability during assembly.

Tflex™ UT20000 provides excellent interfacing and its ability to wet out mating surfaces allows for efficient transfer of heat away from components. It is an ideal choice for low-pressure applications and optimum solution in handheld devices with thin interface gap and limited space requirements.

Tflex™ UT20000 is electrically non-conductive, stable from -50°C thru 200°C and offered in thicknesses that range from 0.008" (200 µm) up to 0.040" (1000 µm).

FEATURES AND BENEFITS

- Thermal Conductivity of 3.0 W/mK
- No fiberglass carrier to minimize thermal resistance, yet still easy to handle
- Excellent surface wetting for low contact resistance
- Unique formulation minimizes thermal resistance at low mounting forces
- Environmentally friendly solution that meets regulatory requirements including RoHS and REACH

SPECIFICATIONS

TYPICAL PROPERTIES	VALUE	TEST METHOD
Construction & Composition	Ceramic filled silicone sheet	N/A
Color	Grey	Visual
Thickness Range	200 µm (0.008")- 1000 µm (0.040")	N/A
Thermal Conductivity (W/mK)	3.0	Hot Disk
Density (g/cc)	3.2	Helium Pyncometer
Hardness (Shore 00)	83.3 (200-375) µm 56.4 (400-1000) µm	ASTM D2240
Outgassing TML (weight %)	0.34%	ASTM E595
Outgassing CVCM (weight %)	0.09%	ASTM E595
Temperature Range	-50°C to 200°C	Laird Test Method
Rth@ 200 µm, 10 psi, 50⁰ C	0.25°C–in2/W	ASTM D5470
Dielectric Constant @ 1MHz	5.87	ASTM D150
UL Flammability Rating	V-0	UL 94
Volume Resistivity	2.2 x 10^15 ohm-cm	ASTM D257

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Asia: +86.755.2714.1166

www.lairdtech.com

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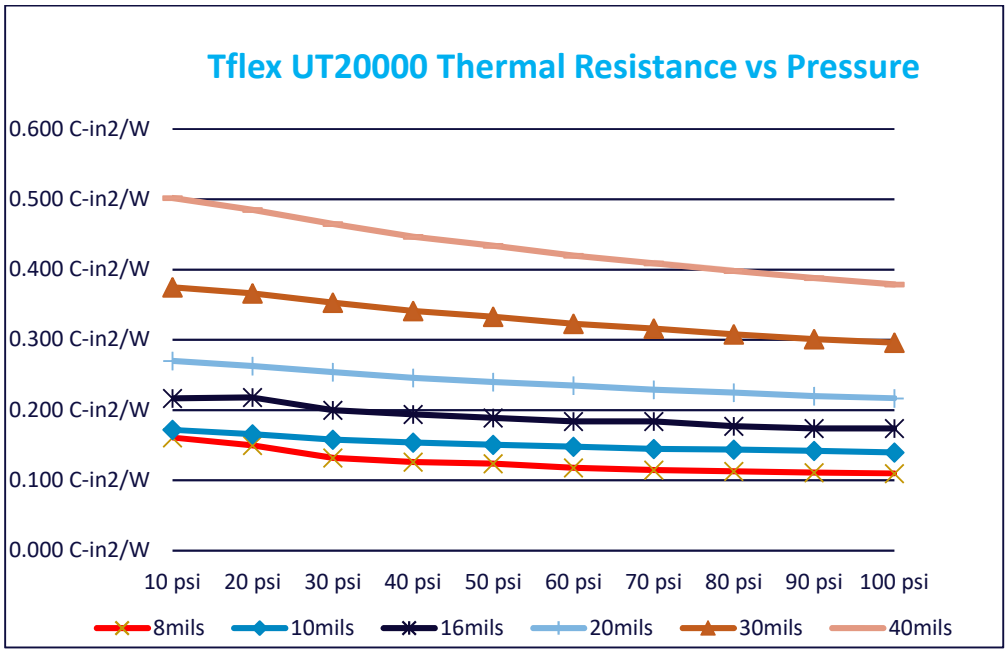

AVAILABILITY

STANDARD THICKNESSES

- 0.008” (200 µm) up to 0.020” (500 µm) thick material available in 25 µm increments
- Also available in 0.025” (625um), 0.030” (750 um), 0.035” (875um) , 0.040” (1000 um)
- Available in standard sheet sizes of 18” x 18” and 9” x 9” or custom die cut parts. Custom die cut parts on a roll available for 200 µm (0.008”) thru 375 µm (0.015”)

PART NUMBER SYSTEM

Tflex™ indicates Laird elastomeric thermal gap filler product line. UT20000 indicates Tflex UT20000 product line with thickness in microns

T f l e x UT2	0 5 0 0
Product code	Pad thickness

µm
0250 => 250µm
0325 => 325µm
0500 => 500µm
1000 => 1000µm

EXAMPLES:

- Tflex™ UT20200= 200 µm (0.008”) thick Tflex™ UT20000 material
- Tflex™ UT20500= 500 µm (0.020”) thick Tflex™ UT20000 material

Laird
Smart Technology. Delivered.™

Tflex UT20000 Series

Ultra-Thin Thermal Gap Filler

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Laird Performance Materials:

A17669-008 A17682-008 A17682-040 A17682-020